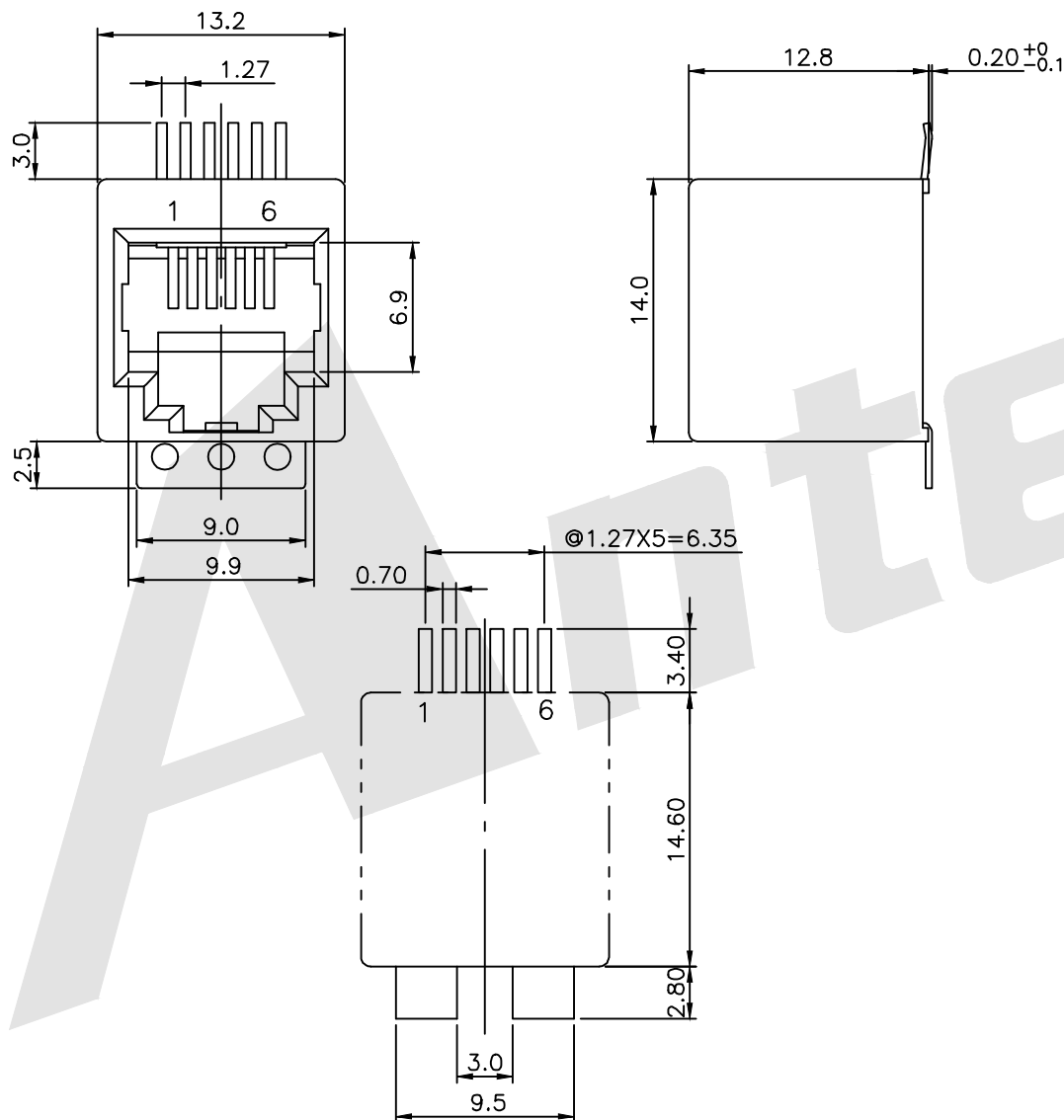


HSF



PCB LAYOUT (COMPONENT SIDE VIEW)

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POLYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE  $t=0.35\text{mm}$
3. PLATING: SELECTING GOLD PLATING  
1u"~50u" OVER NICKEL IN CONTACT AREA. 150u" TIN PLATING OVER NICKEL IN SOLDER AREA.
4. SHIELD: 0.2mm THICKNESS COPPER ALLY WITH NICKEL PLATEL

ELECTRICAL:

1. VOLTAGE RATING: 125 VAC RMS.
2. CURRENT RATING: 1.5 AMP
3. CONTACT RESISTANCE: 30 MILLIOHMS MAX
4. INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500V DC.

5. DIELECTRIC WITHSTANDING RESISTANCE: 1000V AC RMS 60Hz. 1MIN

MECHANICAL:

1. DURRABILITY : 750 CYCLES MIN
2. PCB RETENTION PRE-SOLDER : 10LB MIN

ENVIRONMENTAL:

1. STORAGE: -40°C TO +85°C .
2. OPERATION: -40°C TO +85°C .
3. IR REFLOW SOLDERING TEMPERATURE: 255~265°C (5~10 SECONDS) MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68 SUBPART F.

Order Code:

ATRJ5823 - ① - ② - ③ - ④ - ⑤ - ⑥

- ① SERIES NO:
- ② NUMBER OF POSITIONS (8P, 6P, 4P)
- ③ NUMBER OF CONTACTS (8C, 6C, 4C)
- ④ Contact Plating  
G0: Gold flash  
G1: 3U" Gold  
G2: 5U" Gold  
G3: 10U" Gold  
G4: 15U" Gold  
G5: 30U" Gold  
SN: Tin

- ⑤ Shield  
A: W/O Shield  
B: Half Shield  
C: Shield W/Eml  
D: Shield W/O Eml
- ⑥ packing:  
A: Tray packing  
R: Tape & Reel

Unless Otherwise specified tolerance  
X.  $\pm 0.35$  X.XX:  $\pm 0.20$   
X.X:  $\pm 0.25$  X.XXX:  $\pm 0.15$

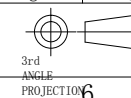
**Antenk**® ANTENK ELECTRONICS CO., LTD  
Http://www.antenk.com  
E-mail:sales@antenk.com

SCALE: As Shown UNIT: mm  
DRAW Wu Feng Rong DATE 22/03/2018  
CHECK BobYang DATE 22/03/2018

TITLE: TOP ENTRY SMT PCB JACK

DRAWING NO: ATRJ5823-6P6C-X-A-X

PRODUCT NO: ATRJ5823-6P6C-X-A-X



REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		